Forged Pin Fin Heat Sinks

Cool Innovations presents the UltraCool III heat sink line parallels the outstanding conceptual design of the UltraCool II line of heat sinks: efficient pin structure resulting in a low thermal resistance, compact size and light weight. Forged from a highly conductive aluminum alloy to allow for superior heat dissipation, the UltraCool III represents an ideal solution for surface mount components dissipating relatively high thermal loads. Designs are available for both natural and forced convection.
The UltraCool III line allows for a high degree of customization. Varying parameters include footprint, pin height, base thickness, pin density and material (copper or aluminum). UltraCool III heat sinks for digital components range from a footprint of 0.3 in. × 0.3 in. to 2.5 in. × 2.5 in. and from a height of 0.2 in. to 1.3 in. An infinite number of combinations within these limits are feasible.
UltraCool III heat sinks are applicable for ASICs, routers, processors, power regulators, DC to DC converters, video and audio processing chips and other "hot" components. They could be attached to packages such as the SOP and SOJ types, BGA, PBGA, QFP, PQFP, PGA, PPGA, and PLCC.

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